

17 (Added) The method of claim 14, wherein providing the optical wave-guide comprises etching or molding a silicon-based material to produce the wave-guide.

18 (Added) The method of claim 14, wherein the substrate comprises at least two layers of materials.

19 (Added) The method of claim 18, wherein the at least two materials comprises silica wafers, dielectric materials, adhesive materials, resins, metals, metal alloys, and composite materials.

20 (Added) The method of claim 14, wherein the wave-guide is a silicon-based material.

IN THE SPECIFICATION

Insert the following before "Field of the Invention":

This application is a divisional of pending application Serial Number 09/752,408, filed December 28, 2000.

REMARKS

No new matter was added by this preliminary amendment.

Please use H0001800 DIV (4960) as the docket number for this application.